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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10002724	10 25 2001	438		2812	<i>W. T. Williams</i>

**APPLICANTS: Madrid Ruben Palacpac Diosdado.

**CONTINUING DATA VERIFIED:

THIS APPLN CLAIMS BENEFIT OF 60/257,939 12/21/2000

PTO-2040
12/99

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiner's initials	<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO TI-27987
TITLE : Method and system for manufacturing ball grid array ("BGA") packages		

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	Print Fig.
TERMINAL		Primary Examiner		
DISCLAIMER		PREPARED FOR ISSUE Application Examiner		
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